

HM5116100 Series — HITACHI/ LOGIC/ARRAYS/MEM

16,777,216-word × 1-bit Dynamic Random Access Memory

The Hitachi HM5116100 is a CMOS dynamic RAM organized 16,777,216 words × 1 bit. It employs the most advanced CMOS technology for high performance and low power. The HM5116100 offers Fast Page Mode as a high speed access mode.

Features

- Single 5 V ($\pm 10\%$)
- High speed
 - Access time
60 ns/ 70 ns/ 80 ns (max)
- Low power dissipation
 - Active mode
440 mW/385 mW/358 mW (max)
 - Standby mode 11 mW (max)
- Fast page mode capability
- Long refresh period
 - 4096 refresh cycles : 64 ms
- 3 variations of refresh
 - $\overline{\text{RAS}}$ -only refresh
 - $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh
 - Hidden refresh
- Test function
 - 16-bit parallel test mode

Ordering Information

Type No.	Access time	Package
HM5116100J-6	60 ns	400-mil 24/28-pin plastic SOJ (CP-24DA)
HM5116100J-7	70 ns	
HM5116100J-8	80 ns	
HM5116100Z-6	60 ns	475-mil 24-pin plastic ZIP (ZP-24A)
HM5116100Z-7	70 ns	
HM5116100Z-8	80 ns	
HM5116100TT-6	60 ns	24/28-pin plastic TSOP II (TTP-24D)
HM5116100TT-7	70 ns	
HM5116100TT-8	80 ns	
HM5116100RR-6	60 ns	
HM5116100RR-7	70 ns	
HM5116100RR-8	80 ns	

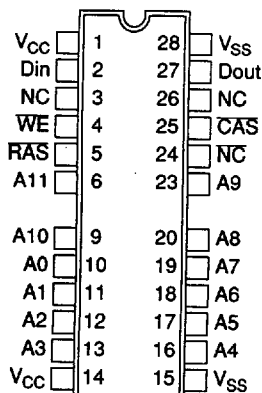
Note: This specification is fully compatible with the 16 Mbit DRAM specifications from TEXAS INSTRUMENTS.

HM5116100 Series

HITACHI/ LOGIC/ARRAYS/MEM

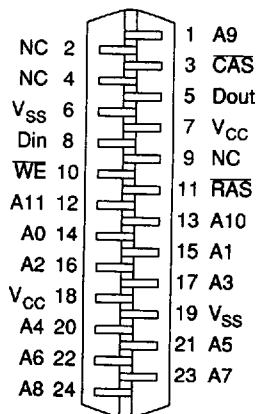
Pin Arrangement

HM5116100J Series



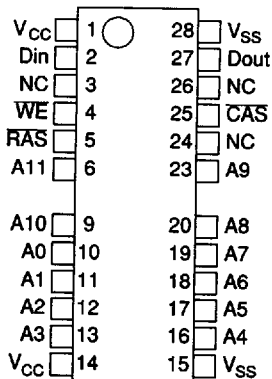
(Top view)

HM5116100Z Series



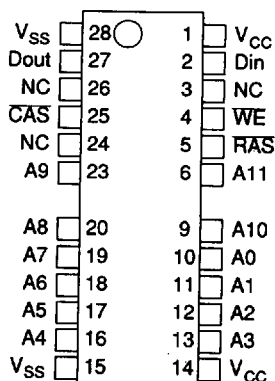
(Bottom view)

HM5116100TT Series



(Top view)

HM5116100RR Series



(Top view)

Pin Description

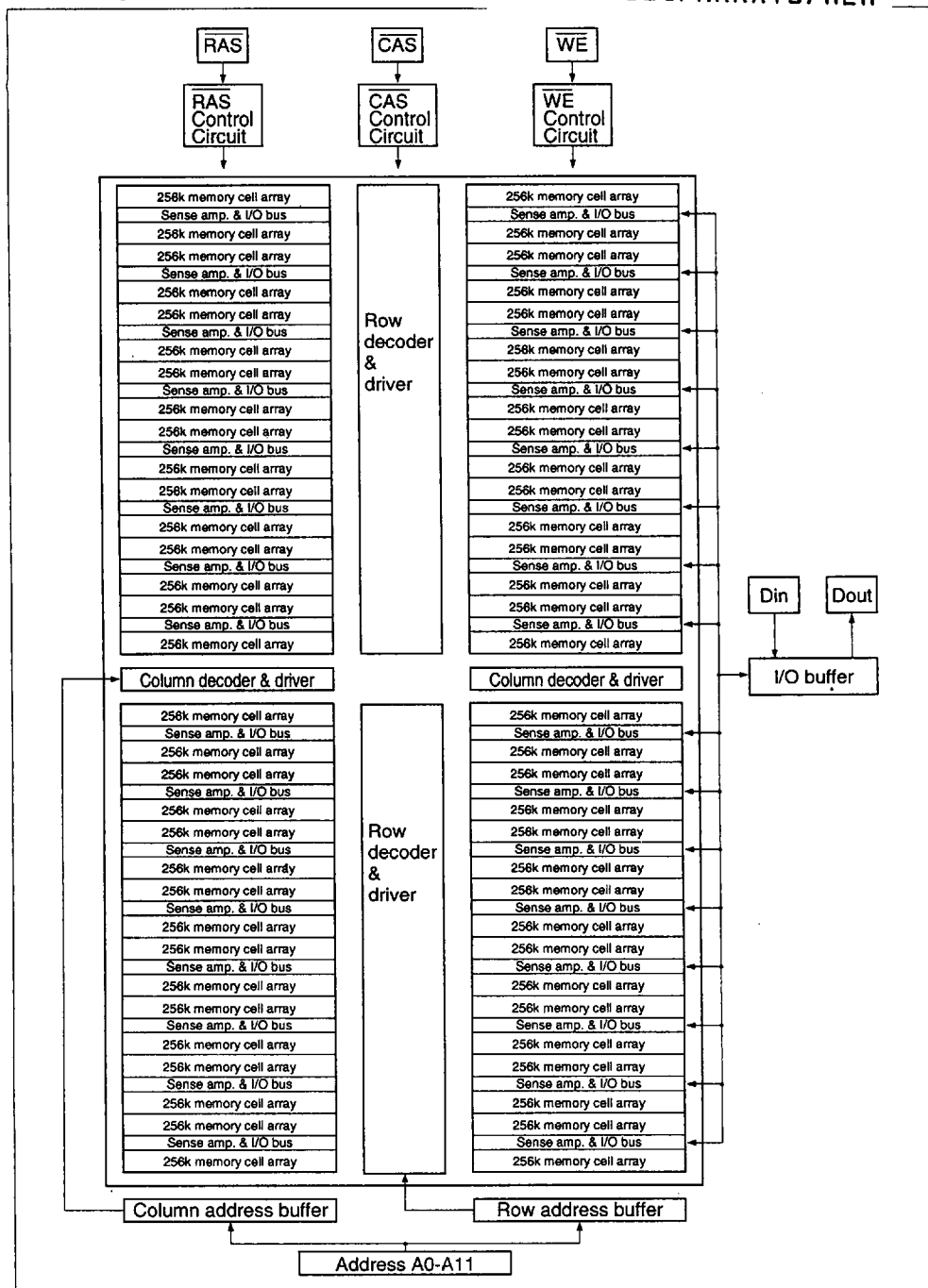
Pin Name	Function
A0 to A11	Address input
A0 to A11	Refresh address input
Din	Data input
Dout	Data output
RAS	Row address strobe

Pin Name	Function
CAS	Column address strobe
WE	Read/write enable
Vcc	Power supply (+5 V)
Vss	Ground
NC	No connection

HM5116100 Series

Block Diagram

HITACHI/ LOGIC/ARRAYS/MEM



HM5116100 Series
HITACHI/ LOGIC/ARRAYS/MEM
Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Voltage on any pin relative to V_{SS}	V_T	-1.0 to +7.0	V
Supply voltage relative to V_{SS}	V_{CC}	-1.0 to +7.0	V
Short circuit output current	I_{out}	50	mA
Power dissipation	P_T	1.0	W
Operating temperature	T_{opr}	0 to +70	°C
Storage temperature	T_{stg}	-55 to +125	°C

Recommended DC Operating Conditions ($T_a = 0$ to +70°C)

Parameter	Symbol	Min	Typ	Max	Unit	Notes
Supply voltage	V_{CC}	4.5	5.0	5.5	V	1
Input high voltage	V_{IH}	2.4	—	6.5	V	1
Input low voltage	V_{IL}	-1.0	—	0.8	V	1

Note : 1. All voltage referenced to V_{SS}

DC Characteristics ($T_a = 0$ to +70°C, $V_{CC} = 5\text{ V} \pm 10\%$, $V_{SS} = 0\text{ V}$)

Parameter	Symbol	HM5116100 -6		HM5116100 -7		HM5116100 -8		Unit	Test condition	Notes
		Min	Max	Min	Max	Min	Max			
Operating current	I_{CC1}	—	80	—	70	—	65	mA	$t_{RC} = \min$	1, 2
Standby current	I_{CC2}	—	2	—	2	—	2	mA	TTL interface RAS, CAS = V_{IH} Dout = High-Z	
		—	1	—	1	—	1	mA	CMOS interface RAS, CAS $\geq$ $V_{CC} - 0.2\text{V}$ Dout = High-Z	
RAS-only refresh current	I_{CC3}	—	80	—	70	—	65	mA	$t_{RC} = \min$	2
Standby current	I_{CC5}	—	5	—	5	—	5	mA	RAS = V_{IH} CAS = V_{IL} Dout = enable	1

HM5116100 Series

DC Characteristics ($T_a = 0$ to $+70^\circ\text{C}$, $V_{CC} = 5\text{ V} \pm 10\%$, $V_{SS} = 0\text{ V}$)(cont)

HM5116100 -6	HM5116100 -7	HM5116100 -8
-----------------	-----------------	-----------------

Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Test condition	Notes
CAS-before-RAS refresh current	I_{CC6}	—	80	—	70	—	65	mA	$t_{RC} = \min$	
Fast page mode current	I_{CC7}	—	80	—	70	—	65	mA	$t_{PC} = \min$	1,3
Input leakage current	I_{LI}	-10	10	-10	10	-10	10	μA	$0\text{ V} \leq V_{in} \leq 7\text{ V}$	
Output leakage current	I_{LO}	-10	10	-10	10	-10	10	μA	$0\text{ V} \leq V_{out} \leq 7\text{ V}$ Dout = disable	
Output high voltage	V_{OH}	2.4	V_{CC}	2.4	V_{CC}	2.4	V_{CC}	V	High Iout = -5 mA	
Output low voltage	V_{OL}	0	0.4	0	0.4	0	0.4	V	Low Iout = 4.2 mA	

Notes : 1. I_{CC} depends on output load condition when the device is selected. I_{CC} max is specified at the output open condition.

2. Address can be changed once or less while $\overline{\text{RAS}} = V_{IL}$.

3. Address can be changed once or less while $\overline{\text{CAS}} = V_{IH}$.

Capacitance ($T_a = 25^\circ\text{C}$, $V_{CC} = 5\text{ V} \pm 10\%$)

Parameter	Symbol	Typ	Max	Unit	Notes
Input capacitance (Address, Data-in)	C_{I1}	—	5	pF	1
Input capacitance (Clocks)	C_{I2}	—	7	pF	1
Output capacitance (Data-out)	C_O	—	7	pF	1,2

Notes : 1. Capacitance measured with Boonton Meter or effective capacitance measuring method.

2. $\overline{\text{CAS}} = V_{IH}$ to disable Dout.

HITACHI/ LOGIC/ARRAYS/MEM

HM5116100 Series

HITACHI/ LOGIC/ARRAYS/MEM
AC Characteristics ($T_a = 0$ to $+70^\circ\text{C}$, $V_{CC} = 5\text{ V} \pm 10\%$, $V_{SS} = 0\text{ V}$) 1), 2), 16)

Test Conditions

Input rise and fall times: 5 ns

Input timing reference levels: 0.8 V, 2.4 V

 Output load: 2 TTL gate + C_L (100 pF)

(Including scope and jig)

Read, write, read-modify-write and refresh cycles (Common parameters)

Parameter	Symbol	HM5116100 -6		HM5116100 -7		HM5116100 -8		Unit	Notes
		Min	Max	Min	Max	Min	Max		
Random read or write cycle time	t_{RC}	110	—	130	—	150	—	ns	
RAS precharge time	t_{RP}	40	—	50	—	60	—	ns	
CAS precharge time	t_{CP}	10	—	10	—	10	—	ns	
RAS pulse width	t_{RAS}	60	10000	70	10000	80	10000	ns	
CAS pulse width	t_{CAS}	15	10000	18	10000	20	10000	ns	
Row address setup time	t_{ASR}	0	—	0	—	0	—	ns	
Row address hold time	t_{RAH}	10	—	10	—	10	—	ns	
Column address setup time	t_{ASC}	0	—	0	—	0	—	ns	
Column address hold time	t_{CAH}	15	—	15	—	15	—	ns	
RAS to CAS delay time	t_{RCD}	20	45	20	52	20	60	ns	3
RAS to column address delay time	t_{RAD}	15	30	15	35	15	40	ns	4
RAS hold time	t_{RSH}	15	—	18	—	20	—	ns	
CAS hold time	t_{CSH}	60	—	70	—	80	—	ns	
CAS to RAS precharge time	t_{CRP}	5	—	5	—	5	—	ns	
Transition time (rise and fall)	t_T	3	30	3	30	3	30	ns	5

HM5116100 Series
Read cycle
HITACHI/ LOGIC/ARRAYS/MEM

Parameter	Symbol	HM5116100 -6		HM5116100 -7		HM5116100 -8		Unit	Notes
		Min	Max	Min	Max	Min	Max		
Access time from $\overline{\text{RAS}}$	t_{RAC}	—	60	—	70	—	80	ns	6, 7, 17
Access time from $\overline{\text{CAS}}$	t_{CAC}	—	15	—	18	—	20	ns	7, 8, 15, 17
Access time from address	t_{AA}	—	30	—	35	—	40	ns	7, 9, 15, 17
Read command setup time	t_{RCS}	0	—	0	—	0	—	ns	
Read command hold time to $\overline{\text{CAS}}$	t_{RCH}	0	—	0	—	0	—	ns	10
Read command hold time to $\overline{\text{RAS}}$	t_{RRH}	5	—	5	—	5	—	ns	10
Column address to $\overline{\text{RAS}}$ lead time	t_{RAL}	30	—	35	—	40	—	ns	
Column address to $\overline{\text{CAS}}$ lead time	t_{CAL}	30	—	35	—	40	—	ns	
$\overline{\text{CAS}}$ to output in low-Z	t_{CLZ}	0	—	0	—	0	—	ns	
Output data hold time	t_{OH}	3	—	3	—	3	—	ns	
Output buffer turn-off time	t_{OFF}	—	15	—	18	—	20	ns	11

Write cycle

Parameter	Symbol	HM5116100 -6		HM5116100 -7		HM5116100 -8		Unit	Notes
		Min	Max	Min	Max	Min	Max		
Write command setup time	t_{WCS}	0	—	0	—	0	—	ns	12
Write command hold time	t_{WCH}	15	—	15	—	15	—	ns	
Write command pulse width	t_{WP}	15	—	15	—	15	—	ns	
Write command to $\overline{\text{RAS}}$ lead time	t_{RWL}	15	—	18	—	20	—	ns	
Write command to $\overline{\text{CAS}}$ lead time	t_{CWL}	15	—	18	—	20	—	ns	
Data-in setup time	t_{DS}	0	—	0	—	0	—	ns	13
Data-in hold time	t_{DH}	15	—	15	—	15	—	ns	13

HM5116100 Series

HITACHI/ LOGIC/ARRAYS/MEM

Read-modify-write cycle

Parameter	Symbol	HM5116100 -6		HM5116100 -7		HM5116100 -8		Unit	Notes
		Min	Max	Min	Max	Min	Max		
Read-modify-write cycle time	t _{RWC}	130	—	153	—	175	—	ns	
RAS to WE delay time	t _{RWD}	60	—	70	—	80	—	ns	12
CAS to WE delay time	t _{CWD}	15	—	18	—	20	—	ns	12
Column address to WE delay time	t _{AWD}	30	—	35	—	40	—	ns	12

Refresh cycle

Parameter	Symbol	HM5116100 -6		HM5116100 -7		HM5116100 -8		Unit	Notes
		Min	Max	Min	Max	Min	Max		
CAS setup time (CBR refresh cycle)	t _{CSR}	10	—	10	—	10	—	ns	
CAS hold time (CBR refresh cycle)	t _{CHR}	20	—	20	—	20	—	ns	
WE setup time (CBR refresh cycle)	t _{WRP}	10	—	10	—	10	—	ns	
WE hold time (CBR refresh cycle)	t _{WRH}	10	—	10	—	10	—	ns	
RAS precharge to CAS hold time	t _{RPC}	0	—	0	—	0	—	ns	

Fast page mode cycle

Parameter	Symbol	HM5116100 -6		HM5116100 -7		HM5116100 -8		Unit	Notes
		Min	Max	Min	Max	Min	Max		
Fast page mode cycle time	t _{PC}	40	—	45	—	50	—	ns	
Fast page mode RAS pulse width	t _{RASP}	—	100000	—	100000	—	100000	ns	14
Access time from CAS precharge	t _{CPA}	—	35	—	40	—	45	ns	7, 15, 17
RAS hold time from CAS precharge	t _{CPRH}	35	—	40	—	45	—	ns	

HITACHI/ LOGIC/ARRAYS/MEM

HM5116100 Series

Fast page mode read-modify-write cycle

Parameter	Symbol	HM5116100 -6		HM5116100 -7		HM5116100 -8		Unit	Notes
		Min	Max	Min	Max	Min	Max		
Fast page mode read-modify-write cycle time	t _{PRWC}	60	—	68	—	75	—	ns	
WE delay time from CAS precharge	t _{CPW}	35	—	40	—	45	—	ns	12

Test mode cycle *16

Parameter	Symbol	HM5116100 -6		HM5116100 -7		HM5116100 -8		Unit	Notes
		Min	Max	Min	Max	Min	Max		
Test mode WE setup time	t _{WTS}	10	—	10	—	10	—	ns	
Test mode WE hold time	t _{WTH}	10	—	10	—	10	—	ns	

Counter test cycle

Parameter	Symbol	HM5116100 -6		HM5116100 -7		HM5116100 -8		Unit	Notes
		Min	Max	Min	Max	Min	Max		
CAS precharge time in counter test cycle	t _{CPT}	40	—	40	—	40	—	ns	

Refresh

Parameter	Symbol	Max	Unit	Notes
Refresh period	t _{REF}	64	ms	4096 cycles

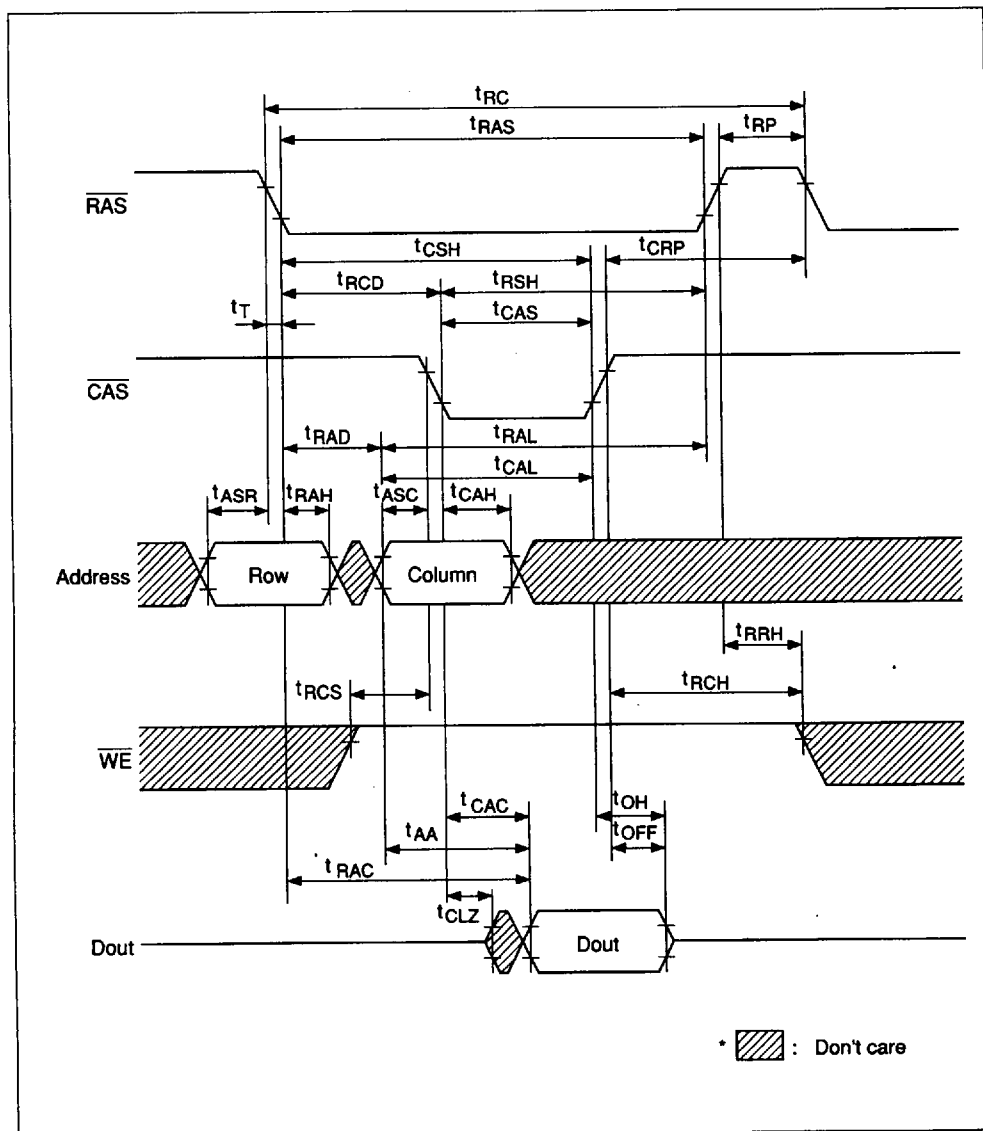
- Notes:
1. AC measurements assume t_T = 5 ns.
 2. An initial pause of 200 μs is required after power up followed by a minimum of eight initialization cycles (any combination of cycles containing RAS-only refresh or CAS-before-RAS refresh). If the internal refresh counter is used, a minimum of eight CAS-before-RAS refresh cycles are required.
 3. Operation with the t_{RCD}(max) limit insures that t_{RAC}(max) can be met, t_{RCD}(max) is specified as a reference point only; if t_{RCD} is greater than the specified t_{RCD}(max) limit, then access time is controlled exclusively by t_{CAC}.
 4. Operation with the t_{RAD}(max) limit insures that t_{RAC}(max) can be met, t_{RAD}(max) is specified as a reference point only; if t_{RAD} is greater than the specified t_{RAD}(max) limit, then access time is controlled exclusively by t_{AA}.
 5. V_{IH}(min) and V_{IL}(max) are reference levels for measuring timing of input signals. Also, transition times are measured between V_{IH}(min) and V_{IL}(max).

HM5116100 Series
HITACHI/ LOGIC/ARRAYS/MEM

6. Assume that $t_{RCD} < t_{RCD(max)}$ and $t_{RAD} < t_{RAD(max)}$. If t_{RCD} or t_{RAD} is greater than the maximum recommended value shown in this table, t_{RAC} exceeds the value shown.
7. Measured with a load circuit equivalent to 2TTL loads and 100 pF.
8. Assume that $t_{RCD} \geq t_{RCD(max)}$ and $t_{RAD} \leq t_{RAD(max)}$.
9. Assume that $t_{RCD} \leq t_{RCD(max)}$ and $t_{RAD} \geq t_{RAD(max)}$.
10. Either t_{RCH} or t_{RRH} must be satisfied for a read cycles.
11. $t_{OFF(max)}$ defines the time at which the output achieves the open circuit condition and is not referenced to output voltage levels.
12. t_{WCS} , t_{RWD} , t_{CWD} , t_{AWD} and t_{CPW} are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only; if $t_{WCS} \geq t_{WCS(min)}$, the cycle is an early write cycle and the data out pin will remain open circuit (high impedance) throughout the entire cycle; if $t_{RWD} \geq t_{RWD(min)}$, $t_{CWD} \geq t_{CWD(min)}$ and $t_{AWD} \geq t_{AWD(min)}$, or $t_{CWD} \geq t_{CWD(min)}$, $t_{AWD} \geq t_{AWD(min)}$ and $t_{CPW} \geq t_{CPW(min)}$, the cycle is a read-modify-write and the data output will contain data read from the selected cell; if neither of the above sets of conditions is satisfied, the condition of the data out (at access time) is indeterminate.
13. These parameters are referenced to $\overline{CAS}$ leading edge in early write cycles and to $\overline{WE}$ leading edge in delayed write or read-modify-write cycles.
14. t_{RASP} defines $\overline{RAS}$ pulse width in fast page mode cycles.
15. Access time is determined by the longer of t_{AA} or t_{CAC} or t_{CPA} .
16. The 16M DRAM offers a 16-bits time saving parallel test mode. Address CA0, CA1, CA10, and CA11 for the 16M $\times$ 1 are don't care during test mode. Test mode is set by performing a $\overline{WE}$ -and- $\overline{CAS}$ -before- $\overline{RAS}$ (WCBR) cycle. In 16-bits parallel test mode, data is written into 16 bits in parallel at Din and read out from Dout.
If 16 bits are equal (all 1s or 0s), data output pin is a high state during test mode read cycle, then the device has passed. If they are not equal, data output pin is a low state, then the device has failed.
Refresh during test mode operation can be performed by normal read cycles or by WCBR refresh cycles.
To get out of test mode and enter a normal operation mode, perform either a regular $\overline{CAS}$ -before- $\overline{RAS}$ refresh cycle or $\overline{RAS}$ -only refresh cycle.
17. In a test mode read cycle, the value of t_{RAC} , t_{AA} , t_{CAC} and t_{CPA} is delayed by 2 ns to 5 ns for the specified value. These parameters should be specified in test mode cycles by adding the above value to the specified value in this data sheet.

HM5116100 Series
Timing Waveforms

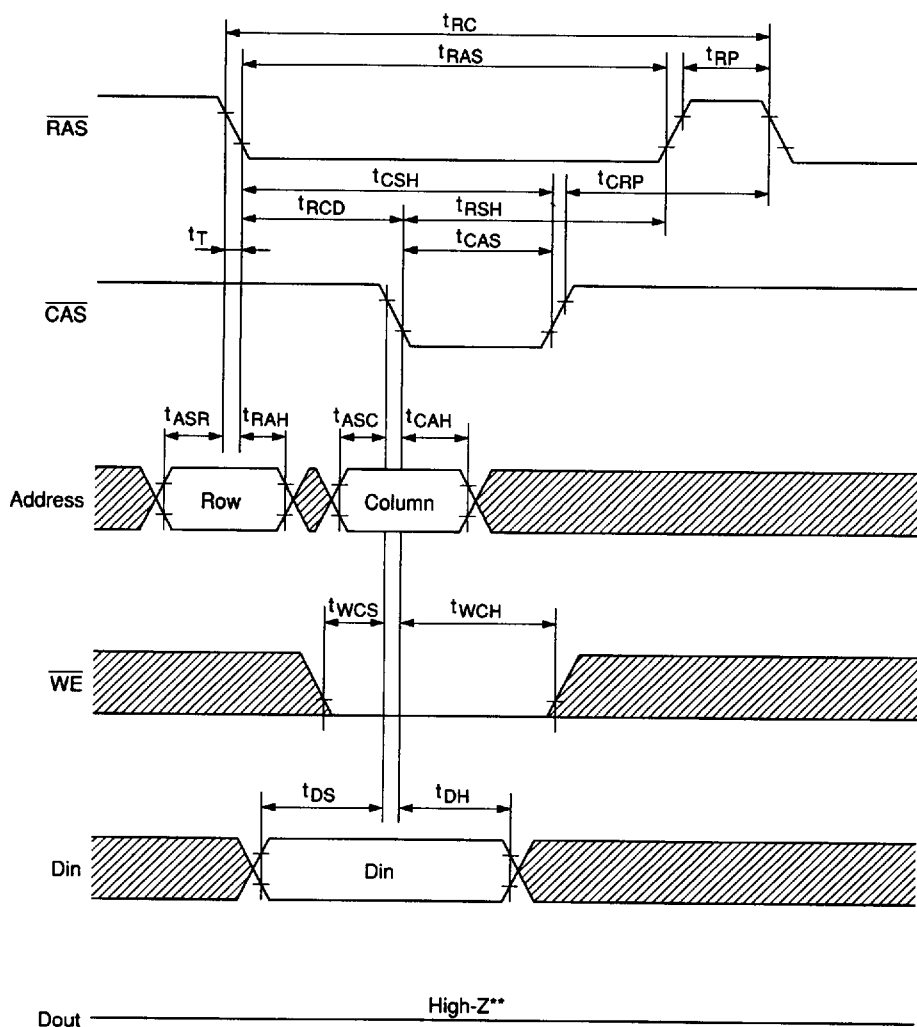
HITACHI/ LOGIC/ARRAYS/MEM

Read Cycle


HM5116100 Series

HITACHI/ LOGIC/ARRAYS/MEM

Early Write Cycle



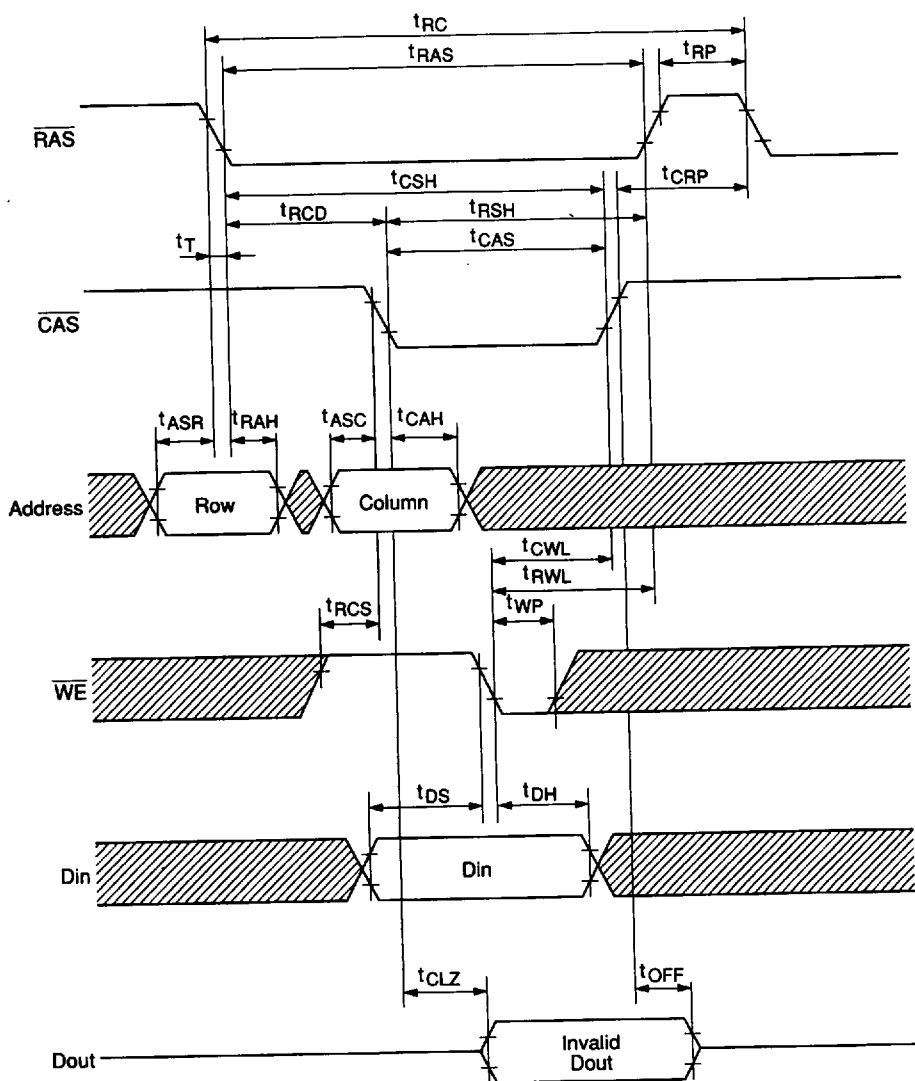
* : Don't care

** $t_{\text{wCS}} \geq t_{\text{wCS}}(\text{min})$

HM5116100 Series

Delayed Write Cycle

HITACHI/ LOGIC/ARRAYS/MEM

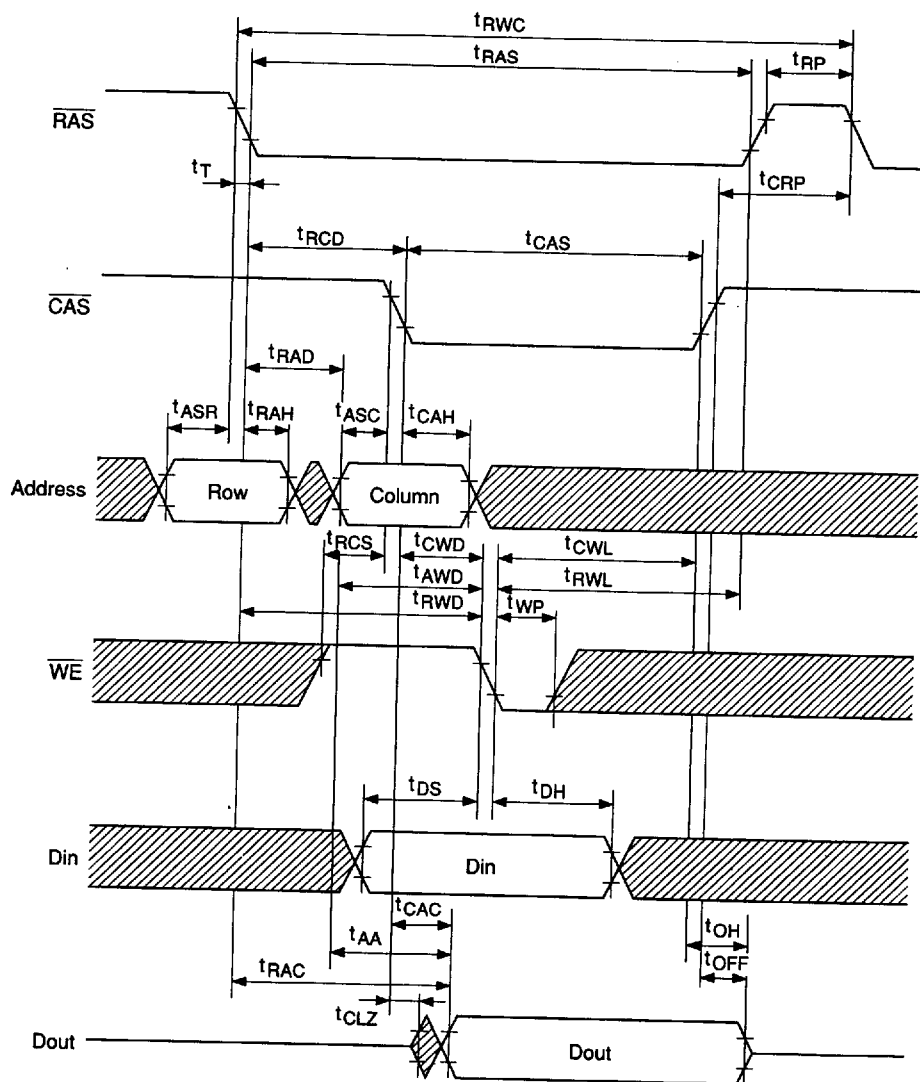


• : Don't care

HM5116100 Series

HITACHI/ LOGIC/ARRAYS/MEM

Read-Modify-Write Cycle

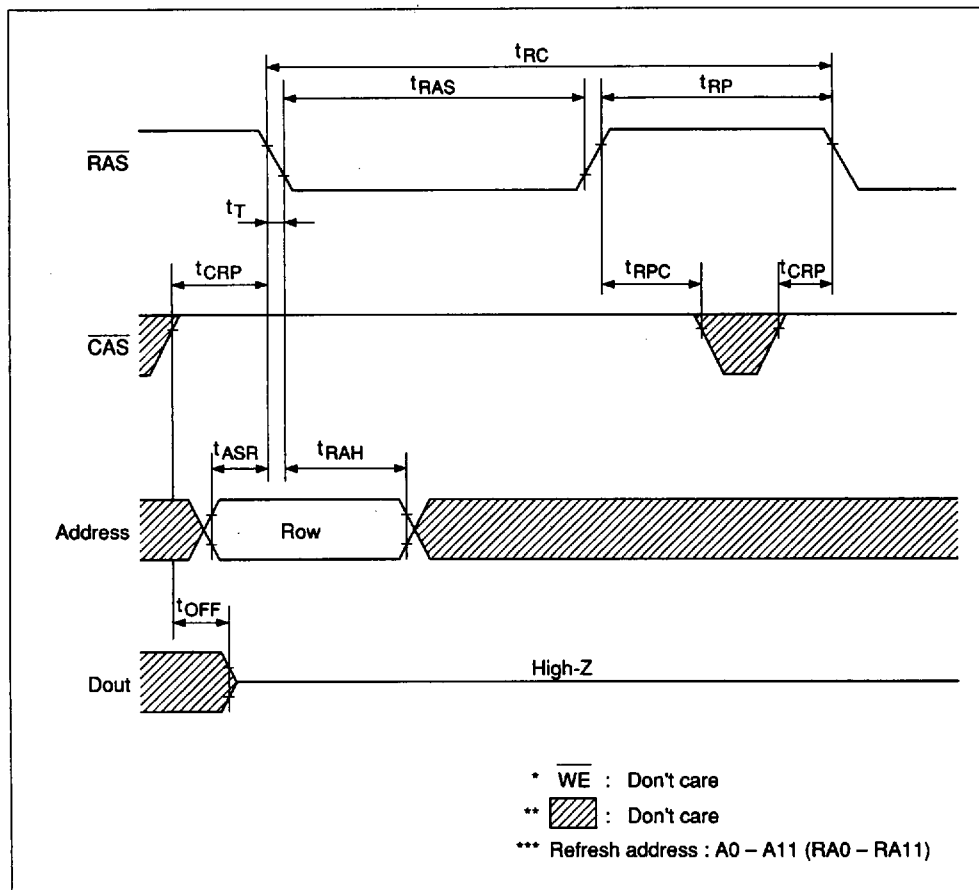


• : Don't care

HM5116100 Series

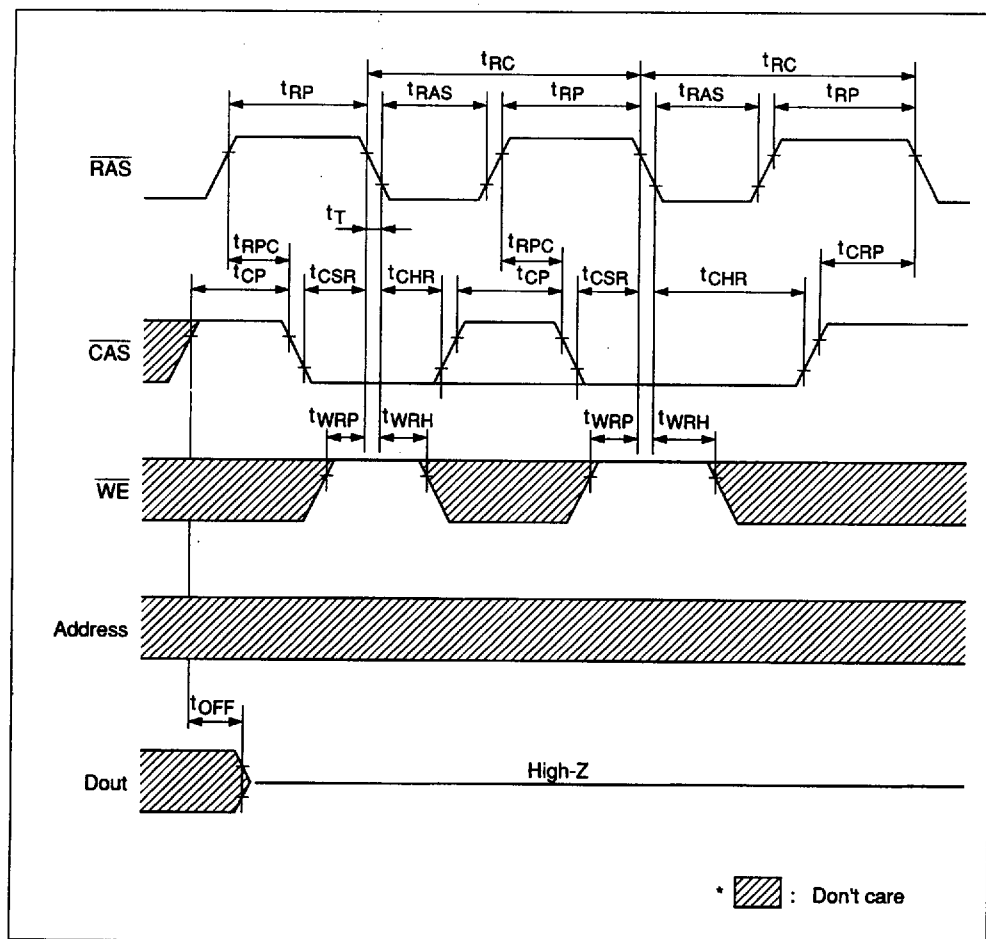
RAS-Only Refresh Cycle

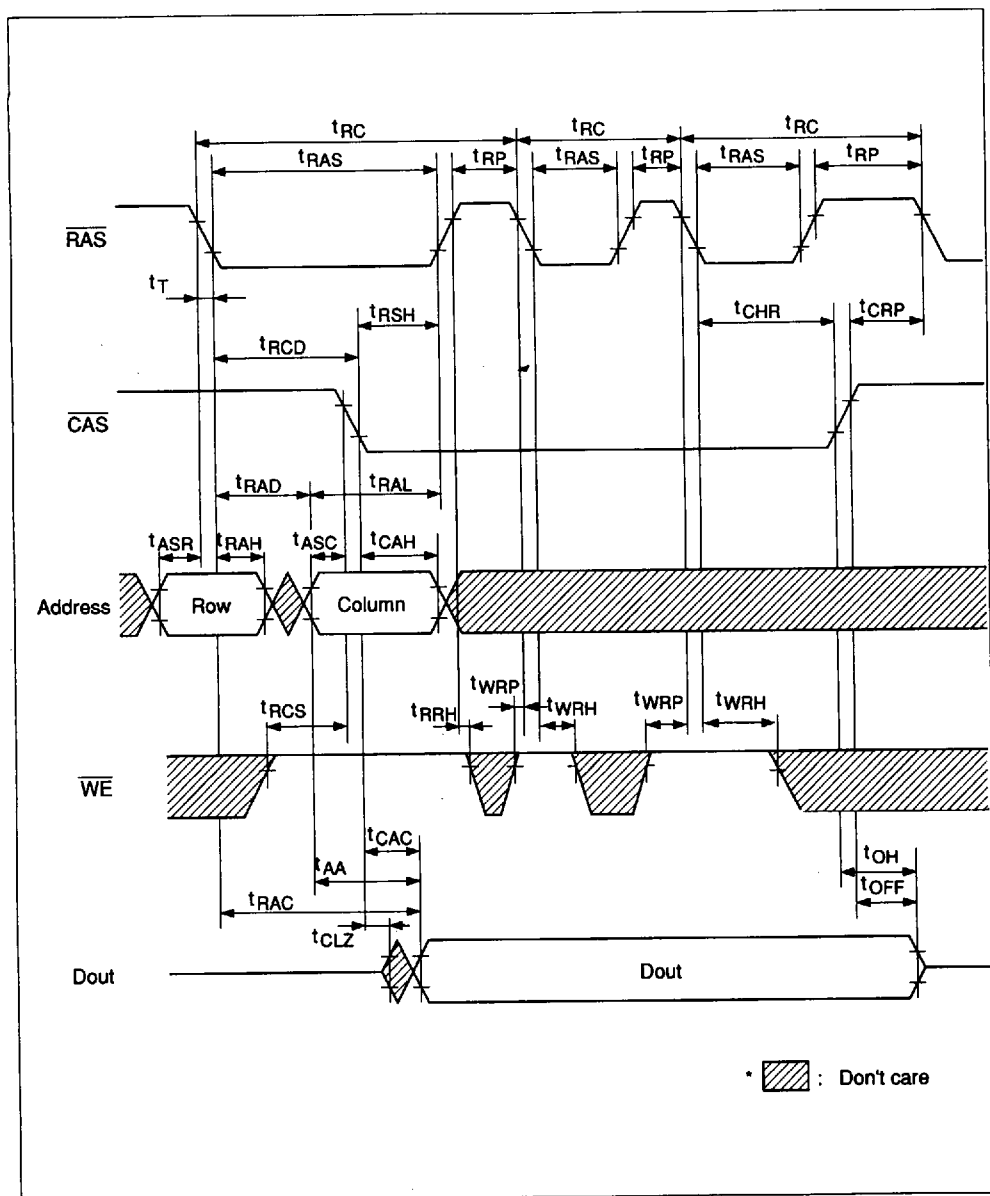
HITACHI/ LOGIC/ARRAYS/MEM



HM5116100 Series

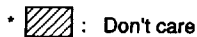
HITACHI/ LOGIC/ARRAYS/MEM

CAS-Before-RAS Refresh Cycle


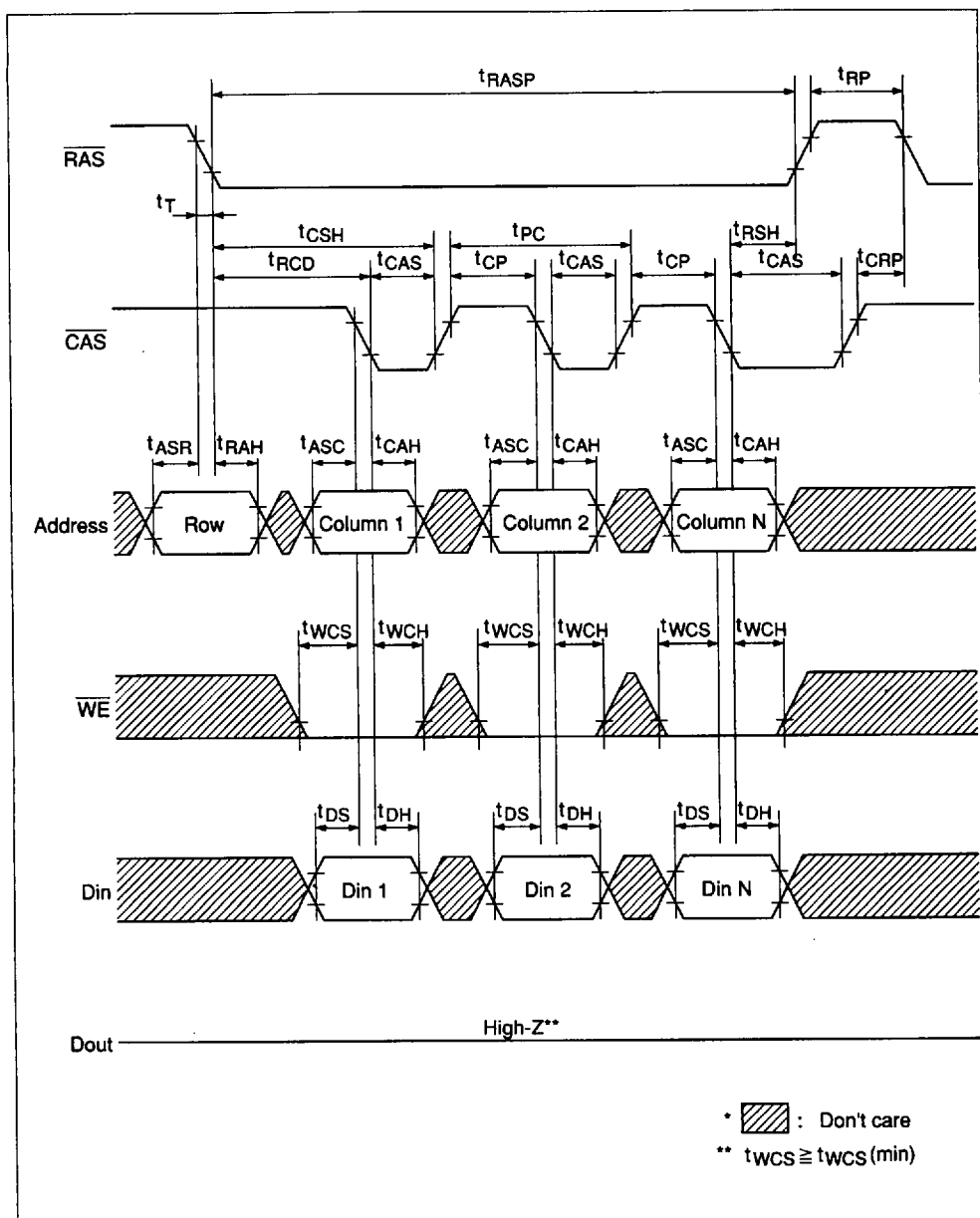
HM5116100 Series
Hidden Refresh Cycle
HITACHI/ LOGIC/ARRAYS/MEM


HITACHI/ LOGIC/ARRAYS/MEM

LOGIC/ARRAYS/MEM



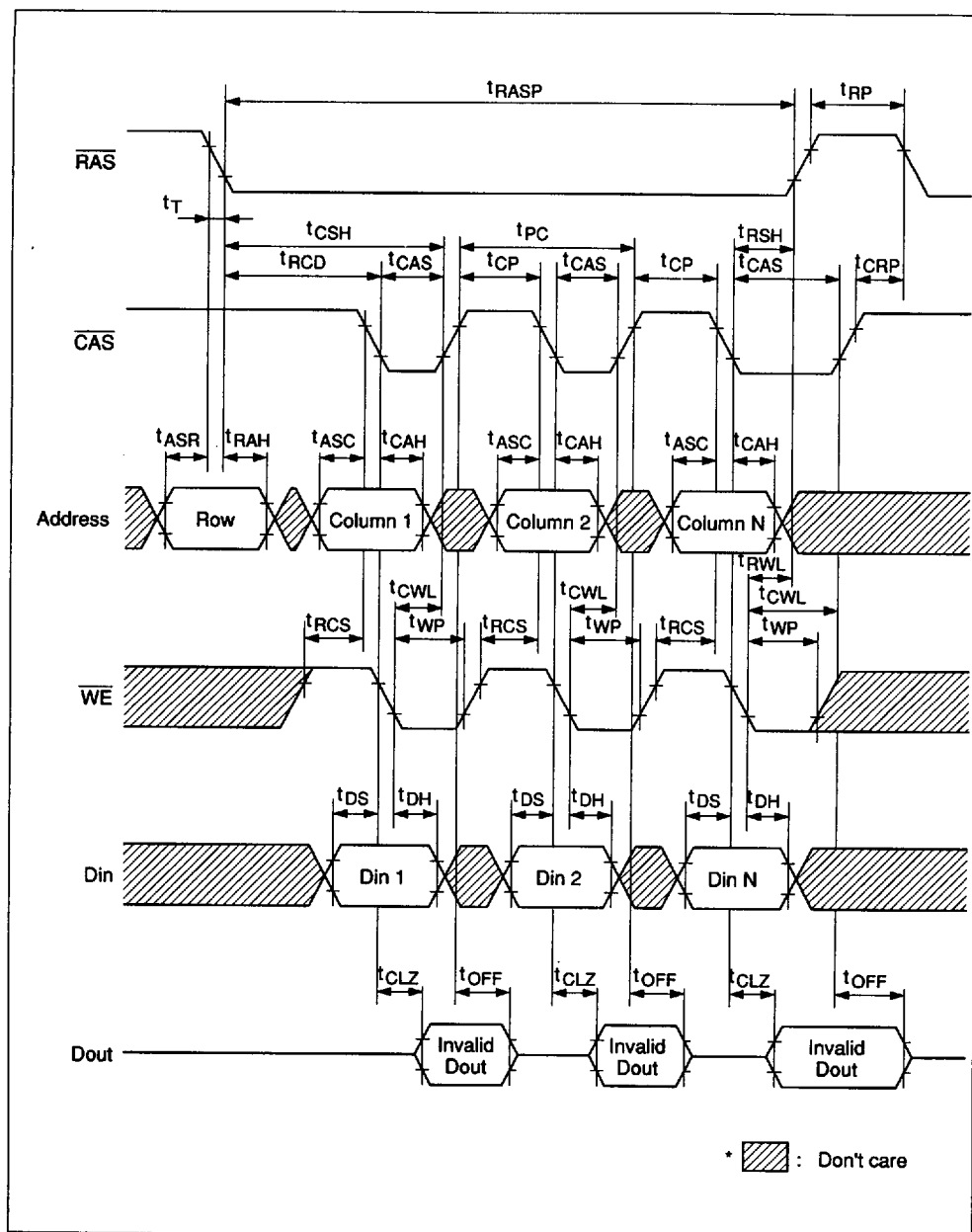
Fast Page Mode Early Write Cycle



HM5116100 Series

HITACHI/ LOGIC/ARRAYS/MEM

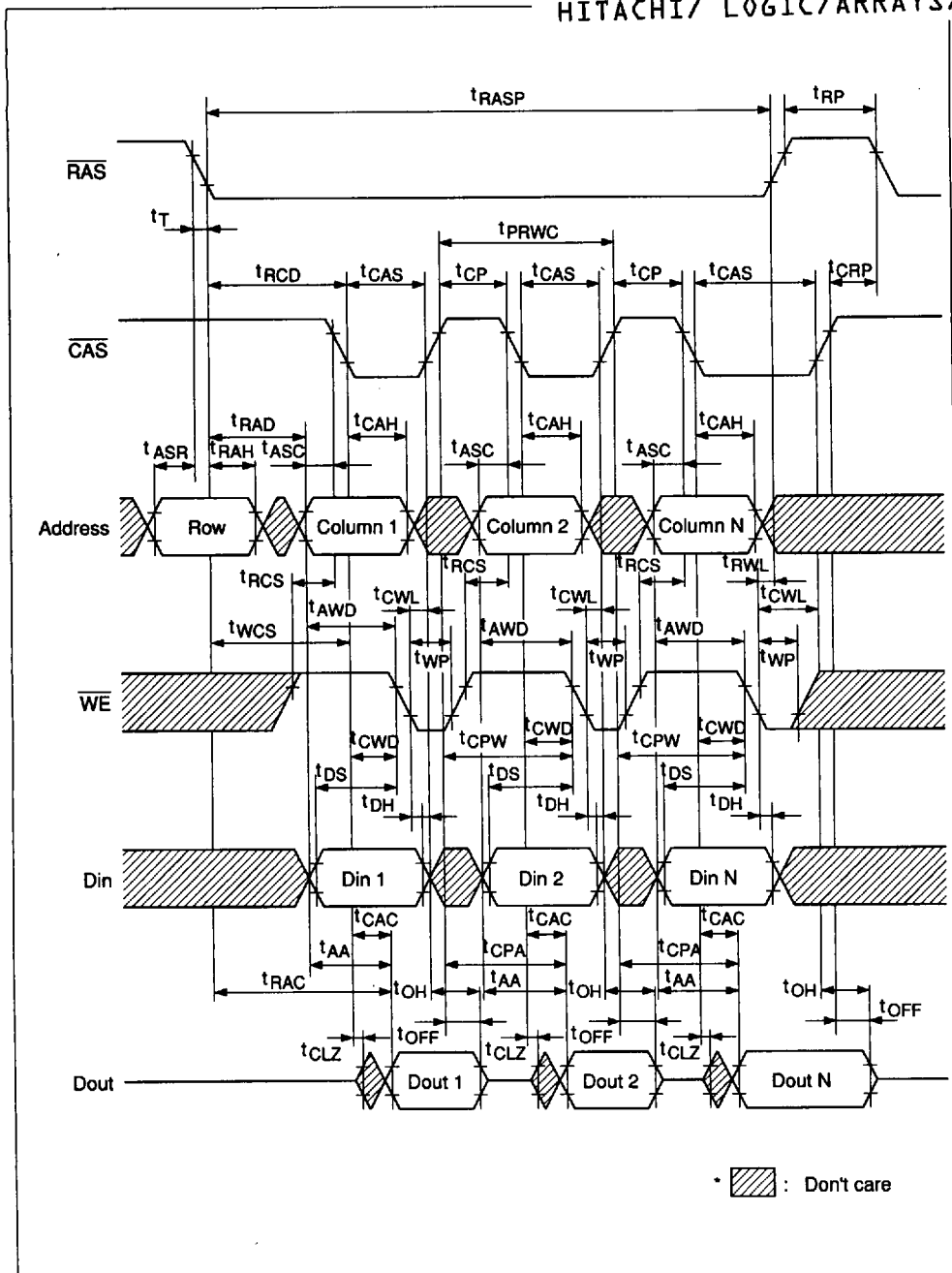
Fast Page Mode Delayed Write Cycle



HM5116100 Series

Fast Page Mode Read-Modify-Write Cycle

HITACHI/ LOGIC/ARRAYS/MEM



HITACHI/ LOGIC/ARRAYS/MEM

Timing diagram for the 6416A SDRAM showing the relationship between RAS, CAS, and WE signals during different operational modes.

The diagram is divided into three main sections:

- Set Cycle*****: The initial refresh cycle where the memory is set to a specific state.
- Test Mode Cycle**: A cycle used for testing the memory's operation.
- Reset Cycle**: A cycle used to reset the memory to its initial state.

The signals shown are:

- RAS**: Row Address Strobe, active-low signal.
- CAS**: Column Address Strobe, active-low signal.
- WE**: Write Enable, active-low signal.

Legend:

- * CBR or $\overline{\text{RAS}}$ only refresh
- ** : Don't care
- *** Address, Din : Don't care

The diagram illustrates the timing relationships for a DRAM. The signals shown are RAS, CAS, WE, Address, and Dout. The timing parameters are defined as follows:

- t_{RP} : RAS precharge time
- t_{RAS} : RAS access time
- t_{RC} : RAS cycle time
- t_{RPC} : RAS precharge to CAS delay
- t_{CSR} : CAS setup time
- t_{CHR} : CAS hold time
- t_T : CAS to RAS delay
- t_{CP} : CAS precharge time
- t_{WTS} : WE setup time
- t_{WTH} : WE hold time
- t_{OFF} : Address setup time
- t_{DQ} : Dout setup time
- t_{DQZ} : Dout hold time
- t_{DQTH} : Dout to High-Z delay

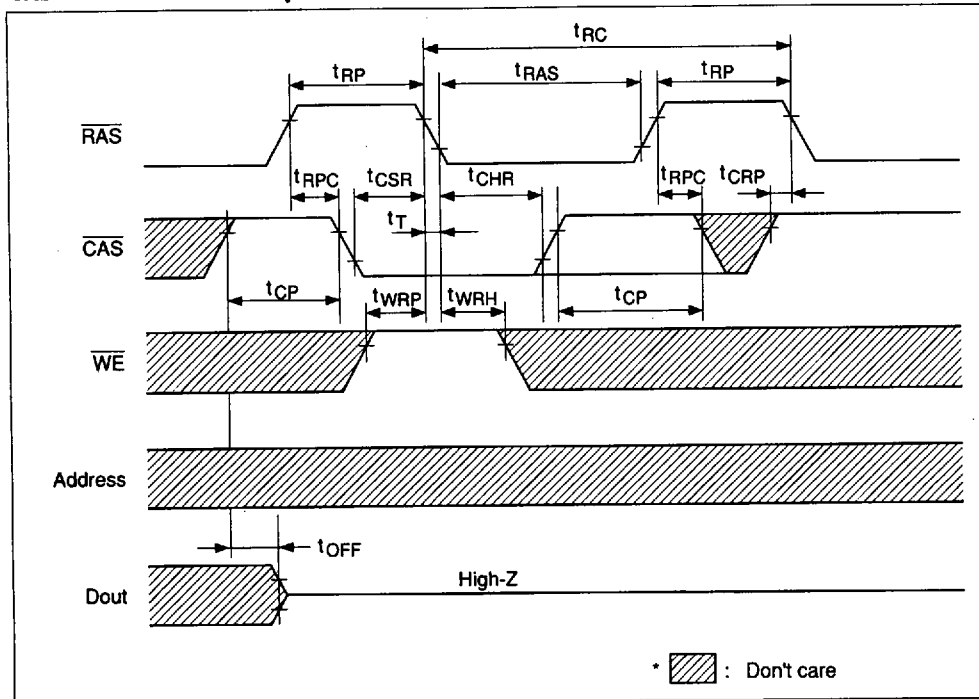
The diagram shows the sequence of operations: RAS precharge, RAS access, RAS precharge, CAS precharge, CAS access, CAS precharge, WE precharge, WE access, WE precharge, Address precharge, Address access, Address precharge, Dout precharge, Dout access, Dout precharge, and High-Z.

HM5116100 Series

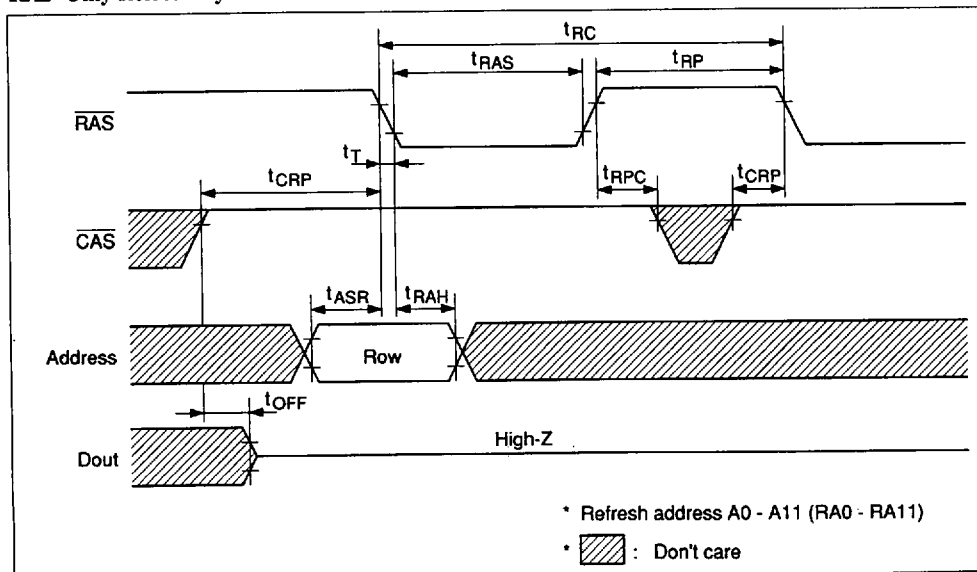
Test Mode Reset Cycle

HITACHI/ LOGIC/ARRAYS/MEM

CAS-Before-RAS Refresh Cycle



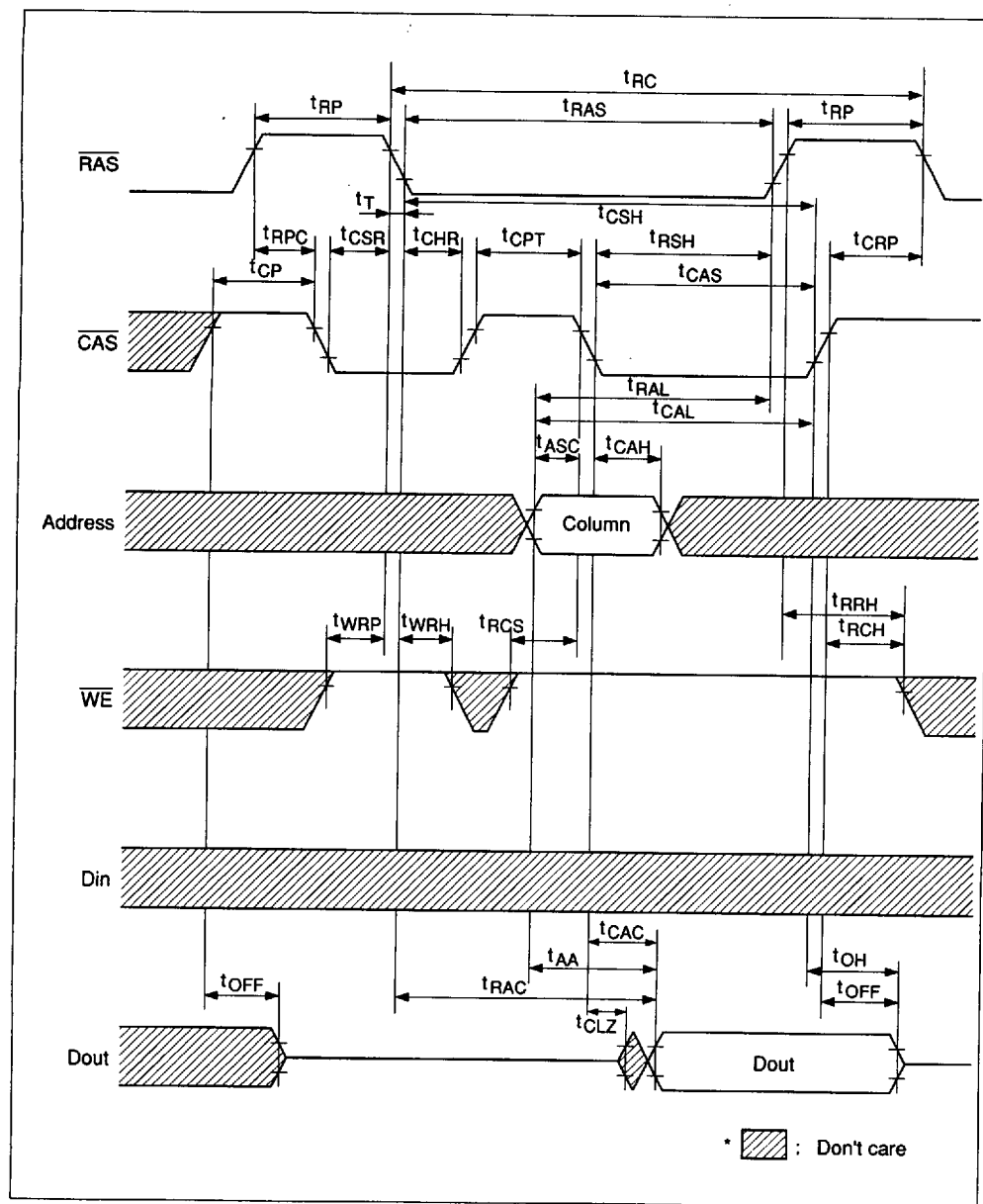
RAS-Only Refresh Cycle



HM5116100 Series

HITACHI/ LOGIC/ARRAYS/MEM

CAS—Before—RAS Refresh Counter Check Cycle (Read)



CAS-Before-RAS Refresh Counter Check Cycle (Write)

